

**REMARKS**

By this Amendment claims 1-5 have been replaced by new claims 6-17 which better define the invention. Entry is requested.

In the final Office Action of February 9, 2006, the examiner rejected claims 1-4 under 35 USC 103(a) as being unpatentable over Gath in view of Feldmann *et al.* and claims 1 and 5 under 35 USC 103(a) as being unpatentable over Hickox in view of Feldmann *et al.*

These rejections cannot apply to new claims 6-17.

Gath discloses an ordinary hearing aid whereby the electronic components are fastened to ordinary flat circuit boards which are inserted between ribs inside an ordinary hearing aid casing to be placed on top of an ear. This patent does not disclose placing leads onto structural moulded parts of the hearing aid for interconnection of electronic placed thereon.

Feldmann *et al.* mention hearing aids but this is in connection with features attributable to the prior art. Thus, Feldmann *et al.* provides no teaching to a person of ordinary skill in this art as to how a hearing aid may be provided with the use of MID technology and the special feature of achieving less of the thin wires used for connecting the transducers in hearing aids. Feldman *et al.* fail to disclose a hearing aid whereby a moulded structural part has a microphone and an amplifier as well as battery connections thereon. This reference only discloses the application of electrical components directly in a product casing. The microphone,

the amplifier and the battery connections which are required to make a working hearing aid are not disclosed.

No combination of Gath and Feldmann *et al.* can be said to suggest the hearing aid as defined in claim 6.

Hickox discloses a customized hearing aid which includes a custom-made casing component 11 and an outer cover or mounting plate component 12, and an inner circuit board component adapted to be secured to the plate 12. The casing is custom made to fit the ear contours of a particular user of the hearing aid. Further, the circuit board is simply a printed circuit board having most of the conductors printed or otherwise formed along one side thereof. Hickox does not disclose a structural moulded part having electric leads which extend along a surface of the structural part to interconnect microphone, amplifier and battery connections whereby the leads, as they extend along the surface of the moulded structural part, are formed on and continuously connected to the moulded structural part. The moulded structural part 11 disclosed in the Hickox document carries no leads on its surface and only serves to enclose the electronics of the device.

Feldmann *et al.* mention hearing aids, but this is in connection with features attributable to the prior art, namely the use of microcircuit carriers. Thus, Feldmann *et al.* do not teach how a hearing aid may be provided with the use of MID technology. This patent does not provide any embodiment information needed for the person of ordinary skill to

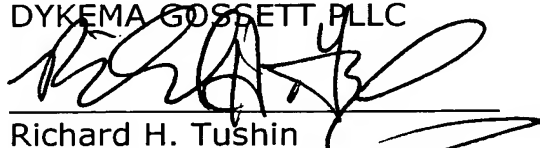
arrive at a hearing aid according to the present invention. Also there is nothing in Feldmann *et al.* which suggests the advantage of fewer electric connection wires inside the hearing aid. These wires are usually provided in order to connect the circuit board and the transducers. When a moulded part is used and the leads are provided on the surface thereof a shorter distance between the transducer connections and the moulded part is realizable and in some cases a transducer such as the microphone may be mounted directly onto the moulded part such that no wires are needed in this case. None of this can be learned from Feldmann *et al.*

No combination of Hickox and Feldmann *et al.* is suggested.

Respectfully submitted,

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